WHAT IS CLAIMED IS:

1. A dividing method of a workpiece by which the workpiece is divided into a plurality of chips and actual dimensions of the chips are detected by a cutting apparatus including

holding means that holds the workpiece having electrodes in each of a plurality of regions marked out by a plurality of planned dividing lines that intersects each other,

cutting means to which a cutting blade that cuts the workpiece held by the holding means is mounted,

imaging means that images the workpiece, and

control means that controls the holding means and the cutting means,

the dividing method comprising:

a dividing step of cutting the workpiece by the cutting blade along the planned dividing lines to divide the workpiece into the plurality of chips;

an image acquisition step of imaging the chips by the imaging means and acquiring an image of the chips; and

a detection step of automatically detecting and calculating the actual dimensions of the chips by the control means based on the images obtained from the image acquisition step, the actual dimensions of the chips

include a size of the whole of the chip, and a position of electrode which the chip has, and a position of an outer circumferential edge of the chip; and

a calculation step of calculating a value that indicates a degree of variation in the actual dimensions of the chips by the control means.

2. The dividing method of a workpiece according to claim 1, wherein

the workpiece is divided in a state of being held by the holding means in the dividing step, and

the workpiece is imaged in a state of being held by the holding means in the image acquisition step.

3. A detection method of dimensions of chips by which a workpiece is divided into a plurality of chips and actual dimensions of the chips are detected by a cutting apparatus including

holding means that holds the workpiece having electrodes in each of a plurality of regions marked out by a plurality of planned dividing lines that intersects each other,

cutting means to which a cutting blade that cuts the workpiece held by the holding means is mounted,

imaging means that images the workpiece, and

control means that controls the holding means and the cutting means,

the detection method comprising:

a dividing step of cutting the workpiece by the cutting blade along the planned dividing lines to divide the workpiece into the plurality of chips;

an image acquisition step of imaging the chips by the imaging means and acquiring an image of the chips;

a detection step of automatically detecting and calculating the actual dimensions of the chips by the control means based on the image obtained from the image acquisition step, the actual dimensions of the chips include a size of the whole of the chip, and a position of electrode which the chip has, and a position of an outer circumferential edge of the chip; and

a calculation step of calculating a value that indicates a degree of variation in the actual dimensions of the chips by the control means.

4. The detection method of dimensions of chips according to claim 3, wherein

the workpiece is divided in a state of being held by the holding means in the dividing step, and

the workpiece is imaged in a state of being held by the holding means in the image acquisition step.

5. A cutting apparatus comprising:

holding means that holds a workpiece;

cutting means to which a cutting blade that cuts the workpiece held by the holding means is mounted;

imaging means that images the workpiece; and

control means that controls the holding means and the cutting means, wherein

the imaging means images the workpiece divided into a plurality of chips by the cutting blade and acquires an image of the chips, and

the control means includes a detecting section that automatically detects and calculates actual dimensions of the chips based on the image, the actual dimensions of the chips include a size of the whole of the chip, and a position of electrode which the chip has, and a position of an outer circumferential edge of the chip;

the control means further includes

a storing section that stores reference values of dimensions of the chips set in advance, and

a calculating section that calculates value that indicates a degree of variation in the actual dimensions of the chips based on the actual dimensions of the chip and the reference values.

6. The cutting apparatus according to claim 5, further comprising:

display means that displays the value calculated in the calculating section.